

APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

**Claim 1 is canceled.**

**The claims are amended as follows:**

2. (Amended) An onboard semiconductor device [according to claim 1, further]  
comprising:  
a power chip circuit board on which a power chip is mounted;  
a control circuit board having mounted thereon an electrical component in relation to said  
power chip;  
an outer case in which said power chip circuit board and the control circuit board are  
contained; and  
fixing means for fixing the control circuit board to the outer case, said fixing means being  
a pawl projectingly provided on the outer case;  
wherein the control circuit board and the outer case are removably fixed to each other.
3. (Amended) An onboard semiconductor device [according to claim 1, further]  
comprising:  
a power chip circuit board on which a power chip is mounted;  
a control circuit board having mounted thereon an electrical component in relation to said  
power chip;

an outer case in which said power chip circuit board and the control circuit board are contained; and

means for electrically connecting the power chip circuit board [circuit board] to the control circuit board [c.b], wherein the [said] connecting means includes a lead electrically connected to the power chip and fixed to the outer case, and a connector attached to the control circuit board [c.b], so as to be fitted to the lead;

wherein the control circuit board and the outer case are removably fixed to each other.

4. (Amended) An onboard semiconductor device [according to claim 1, further] comprising:

a power chip circuit board on which a power chip is mounted;

a control circuit board having mounted thereon an electrical component in relation to said power chip;

an outer case in which said power chip circuit board and the control circuit board are contained; and

means for electrically connecting the power chip circuit board to the control circuit board, wherein the [said] connecting means includes a conductive material member electrically connected to the power chip and fixed to the outer case, a conductive land provided on the control circuit board for connection with the power chip, and an elastic electrical connection material intervening between the conductive material member and the conductive land, and the control circuit board is fixed to the outer case in a state where the electrical connection material is compressed;

wherein the control circuit board and the outer case are removably fixed to each other.

5. (Amended) An onboard semiconductor device [according to claim 1, further]

comprising:

a power chip circuit board on which a power chip is mounted;

a control circuit board having mounted thereon an electrical component in relation to said

power chip;

an outer case in which said power chip circuit board and the control circuit board are

contained; and

means for electrically connecting the power chip circuit board to the control circuit board, wherein said connecting means includes a lead that is electrically connected to the power chip, a lower end portion of which is fixed to the outer case, and which is formed into a spring shape, and the control circuit board is fixed to the outer enclosing case in a state where a tip side of the lead is compressed;

wherein the control circuit board and the outer case are removably fixed to each other.

6. (Amended) An onboard semiconductor device [according to claim 1, further]

comprising:

a power chip circuit board on which a power chip is mounted;

a control circuit board having mounted thereon an electrical component in relation to said

power chip;

an outer case in which said power chip circuit board and the control circuit board are

contained; and

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means for fixing the control circuit board to the outer case, said fixing means being a  
securing member like a screw;

wherein the control circuit board and the outer case are removably fixed to each other.